



SUBSTITUTE SPECIFICATION
APPLICATION NO. 10/761,293
ATTORNEY DOCKET NO. 03599.000089

THREE-DIMENSIONAL STRUCTURE FORMING METHOD

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This application claims a benefit of priority
5 based on Japanese Patent Application No. 2003-014050,
filed on January 22, 2003, which is hereby incorporated
by reference herein in its entirety as if fully set
forth herein.

10 BACKGROUND OF THE INVENTION

The present invention relates, generally, to a
three-dimensional structure forming method, and more
particularly, to a method for forming a three-
15 dimensional structure on a thick, photosensitive resin.

Recent demand for smaller and lower-profile
electronic devices has increasingly required finer
semiconductor devices to be mounted onto these
electronic devices, and a critical dimension has become
20 smaller than 0.15 μm . For this requirement, various
proposals have been made to improve resolving power of
a projection exposure apparatus.

The resolution improves effectively with increased
numerical aperture ("NA") of the projection optical
25 system or higher NA and a shortened wavelength of an
exposure light source. Therefore, exposure light
sources have recently been in transition from the KrF